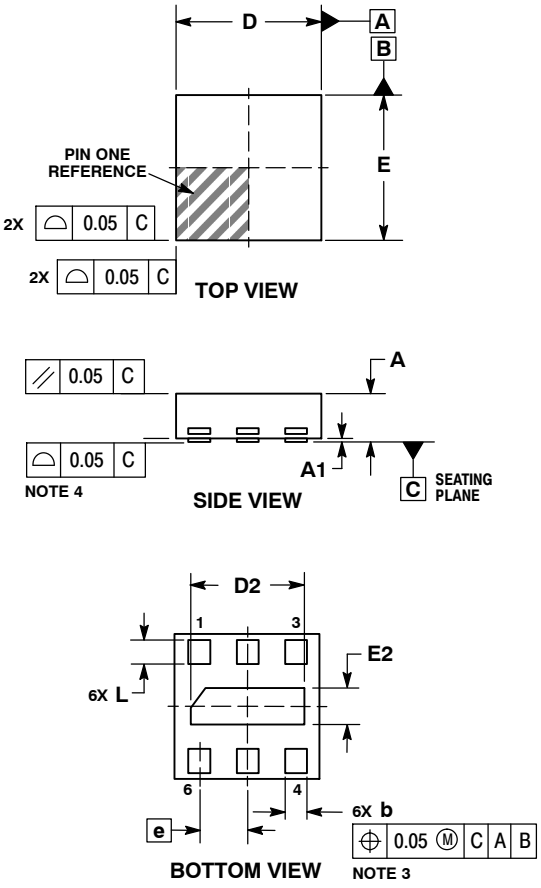
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®

XDFN6 1.20x1.20, 0.40P
CASE 711AH
ISSUE O

SCALE 4:1

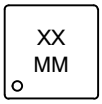
DATE 14 SEP 2011



NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.25mm FROM TERMINAL TIPS.
4. COPLANARITY APPLIES TO ALL OF THE TERMINALS.

	MILLIMETERS	
DIM	MIN	MAX
A	---	0.40
A1	0.00	0.05
b	0.13	0.23
D	1.20 BSC	
D2	0.89	0.99
E	1.20 BSC	
E2	0.25	0.35
e	0.40 BSC	
L	0.15	0.25
L1	0.05 BSC	

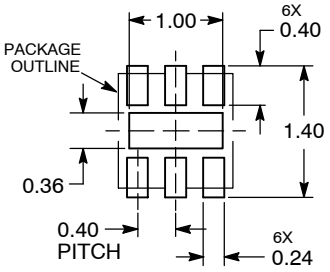
GENERIC MARKING DIAGRAM*



XX = Specific Device Code
MM = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

RECOMMENDED MOUNTING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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